

TITLE: A METHOD FOR FORMING A LOW PROFILE MULTI-IC
CHIP PACKAGE CONNECTOR (as amended)

Inventor: Moden et al.
Serial No.: 10/792,222
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NEW SHEET
10/10

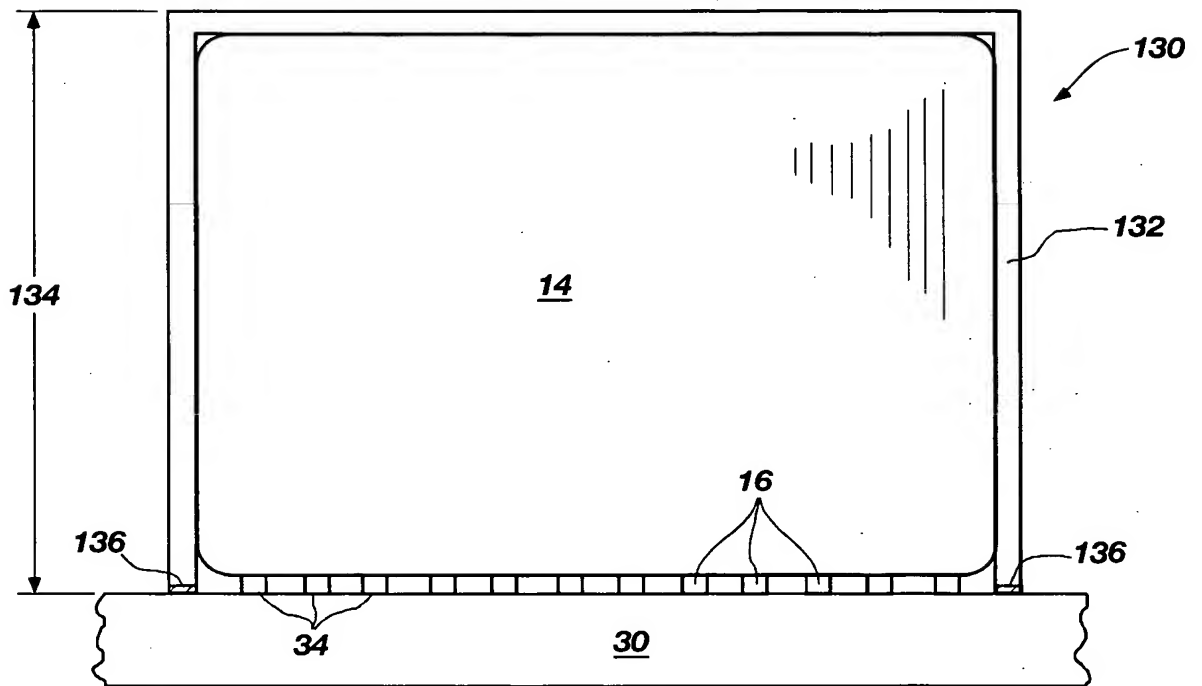


Fig. 14

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